



### 100V N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on) max</sub>	I <sub>D</sub> T <sub>C</sub> = +25°C	
100V	$80m\Omega$ @ $V_{GS}$ = $10V$	17A	
	99mΩ @ V <sub>GS</sub> = 6V	15A	

### **Description**

This new generation complementary MOSFET features low on-resistance and fast switching, making it ideal for high efficiency power management applications.

## **Applications**

- **Power Management Functions**
- DC-DC Converters

## **Features**

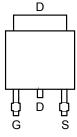
- Low  $R_{DS(ON)}$  ensures on state losses are minimized
- Small form factor thermally efficient package enables higher density end products
- Lead-Free Finish; RoHS compliant (Note 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

### **Mechanical Data**

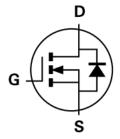
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe Solderable per MIL-STD-202. Method 208 @3
- Weight: 0.33 grams (approximate)











Internal Schematic

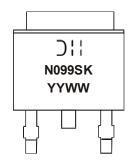
## Ordering Information (Note 4)

Part Number	Case	Packaging
DMN10H099SK3-13	TO252	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



⊃ : l'=Manufacturer's Marking N099SK = Product Type Marking Code YYWW = Date Code Marking YY = Last Digit of Year (ex: 14 = 2014)WW = Week Code (01 to 53)



# **Maximum Ratings** ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic		Symbol	Value	Units
Drain-Source Voltage		$V_{DSS}$	100	V
Gate-Source Voltage		$V_{GSS}$	±20	V
Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V	$T_C = +25$ °C $T_C = +70$ °C	Ι <sub>D</sub>	17 13	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	20	Α	
Avalanche Current, L = 1mH		I <sub>AS</sub>	7.5	Α
Avalanche Energy, L = 1mH		E <sub>AS</sub>	28.5	mJ

# Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Total Power Dissipation (Note 5)	T <sub>C</sub> = +25°C	D	34	- W
Total Power Dissipation (Note 5)	T <sub>C</sub> = +70°C	$P_{D}$	22	
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>0JA</sub>	51	°C/W	
Thermal Resistance, Junction to Case (Note 5)	R <sub>0</sub> JC	3.6	C/vv	
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

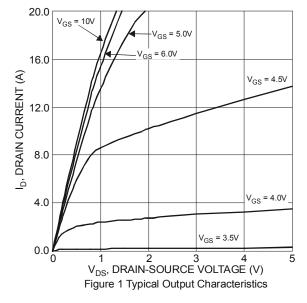
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

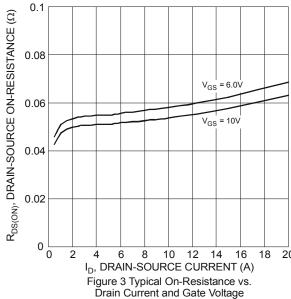
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	100	_	_	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μA	V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.5	2	3	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	Ь	_	67	80	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.3A	
Static Dialii-Source Off-Resistance	R <sub>DS (ON)</sub>	_	69	99	11122	$V_{GS} = 6V, I_D = 3A$	
Diode Forward Voltage	$V_{SD}$		0.77	_	V	$V_{GS} = 0V, I_S = 3.2A$	
DYNAMIC CHARACTERISTICS (Note 6)							
Input Capacitance	C <sub>iss</sub>		1172	_		$V_{DS} = 50V, V_{GS} = 0V, f = 1MHz$	
Output Capacitance	Coss		40.8	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	31.3	_			
Gate Resistance	$R_G$		1.6	_	Ω	$V_{DS}$ = 0V, $V_{GS}$ = 0V, f = 1MHz	
Total Gate Charge (V <sub>GS</sub> = 10V)	$Q_g$		25.2	_			
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_g$		12.2	_	nC	$V_{DS} = 50V, I_D = 3.3A$	
Gate-Source Charge	$Q_{gs}$	_	5.3	_	110		
Gate-Drain Charge	$Q_{gd}$		5.9	_			
Turn-On Delay Time	t <sub>D(on)</sub>		5.4	_		$V_{DD}$ = 50V, $R_{G}$ = 6.0 $\Omega$ , $I_{D}$ = 3.3A	
Turn-On Rise Time	t <sub>r</sub>	_	5.9	_	ns		
Turn-Off Delay Time	t <sub>D(off)</sub>	_	20	_	115		
Turn-Off Fall Time	t <sub>f</sub>		7.3	_			
Body Diode Reverse Recovery Time	t <sub>rr</sub>	_	19.7	_	ns	L = 2.24 dl/dt = 1004/up	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>		15.9	_	nC	I <sub>F</sub> = 3.3A, dl/dt = 100A/μs	

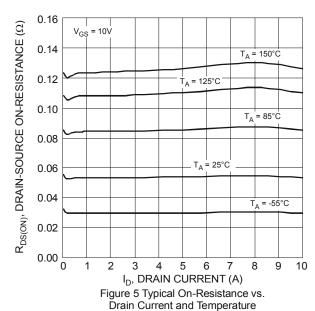
5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:

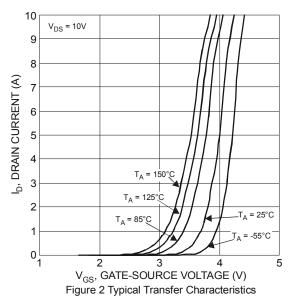
Guaranteed by design. Not subject to product testing.
 Short duration pulse test used to minimize self-heating effect.

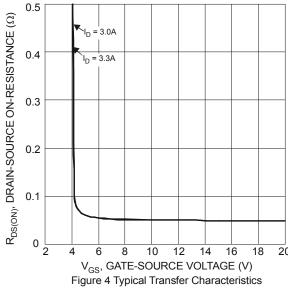


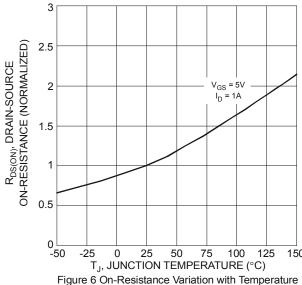




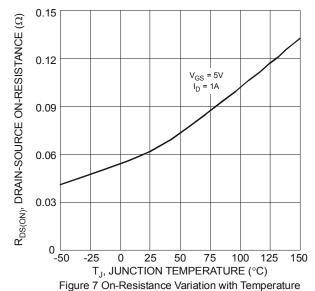


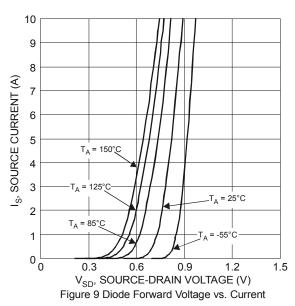


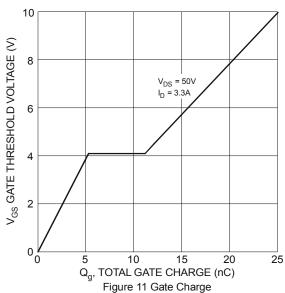












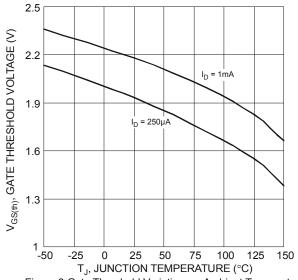
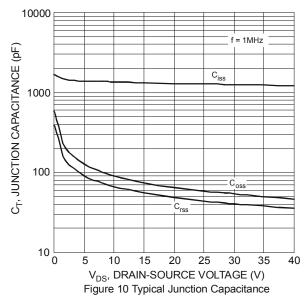
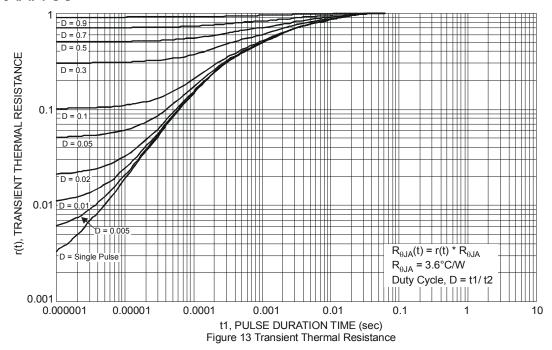


Figure 8 Gate Threshold Variation vs. Ambient Temperature



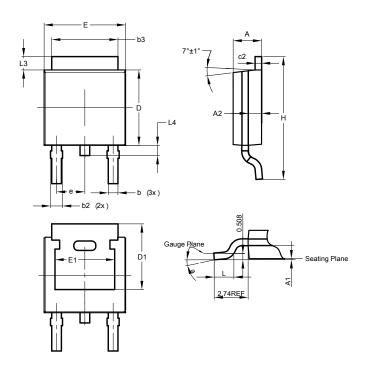
100
R<sub>DS(on)</sub>
Limited
P<sub>W</sub> = 1µs
P<sub>W</sub> = 1µs
P<sub>W</sub> = 100ms
P<sub>W</sub> = 100ms
P<sub>W</sub> = 100ms
P<sub>W</sub> = 100µs





# **Package Outline Dimensions**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.

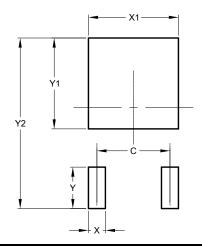


TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
c2	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	-	-		
е	-	-	2.286		
Е	6.45	6.70	6.58		
E1	4.32	-	-		
Н	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All Dimensions in mm					



### Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
С	4.572		
Х	1.060		
X1	5.632		
Y	2.600		
Y1	5.700		
Y2	10.700		

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